

Please add the following amended Abstract of the Disclosure.

ABSTRACT OF THE DISCLOSURE

An RFID tag includes a substrate having a top surface and a bottom surface. An RFID integrated circuit is disposed on the top surface of the substrate. A first electrically conductive region is associated with the top surface of the substrate and electrically coupled to the RFID integrated circuit. A second electrically conductive region is associated with the bottom surface of the substrate and electrically coupled to the first conductive region, the first and second conductive regions forming an RFID antenna. The RFID integrated circuit, first conductive region and second conductive region together provide an RFID function. An attachment layer is associated with the bottom surface of the substrate for attaching the tag to a surface. An adhesion modifying layer modifies the adhesion of the second conductive region such that the second conductive region is disrupted if the tag is tampered or removed from the surface.